

**FEE TRANSMITTAL**

Electronic Version v08

Stylesheet Version v08.0

**Title of  
Invention****[FLIP-CHIP PACKAGE SUBSTRATE AND FLIP-CHIP BONDING PROCESS  
THEREOF]**

Application Number :

Date :

First Named Applicant: Mr. Min-Lung Huang

Attorney Docket Number: 10788-US-PA

**TOTAL FEE AUTHORIZED \$ 810**

Patent fees are subject to annual revisions on or about October 1st of each year.

Filing as large entity

**BASIC FILING FEE**

Fee Description	Fee Code	Amount \$	Fee Paid \$
Utility Filing Fee	1001	770	770
Subtotal For Basic Filing Fees: \$ 770			

**EXTRA CLAIM FEES**

Fee Description	Extra Claim	Fee Code	Amount \$	Fee Paid \$
Total Claims : 14	0	1202	18	0
Independent Claims : 2	0	1201	86	0
Subtotal For Extra Claims Fees: \$ 0				

**ASSIGNMENT FEES**

Fee Description	Property Number	Quantity	Fee Code	Amount \$	Fee Paid \$
Recording Each Patent Assignment Per Property Fee	00000000	1	8021	40	40
Subtotal For Additional Fees: \$40					

**AUTHORIZED BILLING INFORMATION****The commissioner is hereby authorized to charge indicated fees and credit any overpayments to:**

Credit account number: 1000  
Expiration Date (YYYYMMDD): 2006-10-31  
Authorized name: LEE, HUAI-LU  
Billing address: 99999